

FEATURES

- Tiny, 3.35 mm × 2.50 mm × 0.88 mm surface-mount package**
- Omnidirectional response**
- Very high SNR of 65 dBA**
- Sensitivity of -38 dBV**
- Extended frequency response from 100 Hz to 20 kHz**
- Low current consumption: 180 μA**
- Single-ended analog output**
- 120 dB maximum SPL**
- High PSR of 70 dBV**
- Compatible with Sn/Pb and Pb-free solder processes**
- RoHS/WEEE compliant**

APPLICATIONS

- Smartphones and feature phones**
- Tablet computers**
- Teleconferencing systems**
- Digital still and video cameras**
- Bluetooth headsets**
- Notebook PCs**
- Security and surveillance**

GENERAL DESCRIPTION

The [ADMP504](#)¹ is a high performance, very low noise, low power, analog output, bottom-ported omnidirectional MEMS microphone. The [ADMP504](#) consists of a MEMS microphone element, an impedance converter and an output amplifier. The [ADMP504](#) sensitivity specification makes it an excellent choice for both near field and far field applications. The [ADMP504](#) is function- and pin-compatible with the [ADMP404](#) microphone, providing an easy upgrade path.

The [ADMP504](#) has very high SNR and extended wideband frequency response, resulting in natural sound with high

intelligibility. Low current consumption enables long battery life for portable applications. The [ADMP504](#) complies with the TIA-920 *Telecommunications Telephone Terminal Equipment Transmission Requirements for Wideband Digital Wireline Telephones* standard.

The [ADMP504](#) is available in an ultraminiature 3.35 mm × 2.5 mm × 0.88 mm surface-mount package. It is reflow solder compatible with no sensitivity degradation. The [ADMP504](#) is halide free.

FUNCTIONAL BLOCK DIAGRAM

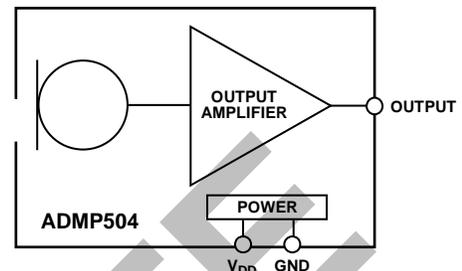
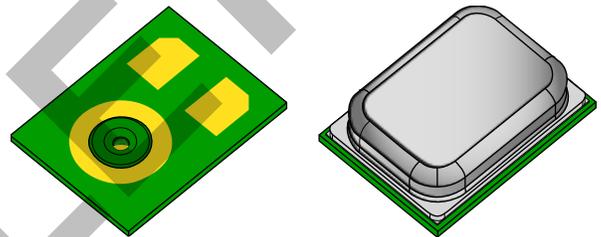


Figure 1.


 Figure 2. Isometric Views of [ADMP504](#) Microphone Package

¹ Protected by U.S. Patents 7,449,356; 7,825,484; 7,885,423; 7,961,897. Other patents are pending.

Rev. A

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REVISION HISTORY

6/12—Rev. 0 to Rev. A

Changes to Figure 2.....	1
Changes to General Description Section	1
Change to Power Supply Rejection Parameter, Table 1	3
Changes to Supporting Documents Section	7
Changes to Reflow Solder Section.....	8

10/11—Revision 0: Initial Version

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SPECIFICATIONS

$T_A = 25^\circ\text{C}$, $V_{DD} = 1.8\text{ V}$, unless otherwise noted. All minimum and maximum specifications are guaranteed. Typical specifications are not guaranteed.

Table 1.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
PERFORMANCE						
Directionality				Omni		
Sensitivity		1 kHz, 94 dB SPL	-41	-38	-35	dBV
Signal-to-Noise Ratio	SNR	20 Hz to 20 kHz, A-weighted		65		dBA
Equivalent Input Noise	EIN	20 Hz to 20 kHz, A-weighted		29		dBA SPL
Dynamic Range		Derived from EIN and maximum acoustic input		91		dB
Frequency Response ¹		Low frequency -3 dB point		100		Hz
		High frequency -3 dB point		>20		kHz
Total Harmonic Distortion	THD	104 dB SPL			3	%
Power Supply Rejection	PSR	217 Hz, 100 mV p-p square wave superimposed on $V_{DD} = 1.8\text{ V}$		-70		dBV
Maximum Acoustic Input		Peak, 10% THD		120		dB SPL
POWER SUPPLY						
Supply Voltage	V_{DD}		1.6		3.3	V
Supply Current	I_S	$V_{DD} = 1.8\text{ V}$		180	200	μA
		$V_{DD} = 3.3\text{ V}$		200	225	μA
OUTPUT CHARACTERISTICS						
Output Impedance	Z_{OUT}			200		Ω
Output DC Offset				0.8		V
Output Current Limit				90		μA
Maximum Output Voltage		120 dB SPL input, peak		0.25		V
Noise Floor		20 Hz to 20 kHz, A-weighted, rms		-103		dBV

¹ See Figure 5 and Figure 7.

ABSOLUTE MAXIMUM RATINGS

Table 2.

Parameter	Rating
Supply Voltage	-0.3 V to +3.6 V
Sound Pressure Level (SPL)	160 dB
Mechanical Shock	10,000 g
Vibration	Per MIL-STD-883 Method 2007, Test Condition B
Temperature Range	-40°C to +85°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

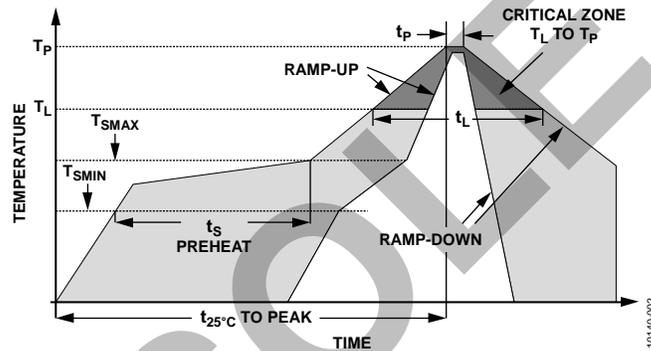
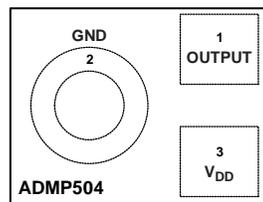


Figure 3. Recommended Soldering Profile Limits

Table 3. Recommended Soldering Profile Limits

Profile Feature	Sn63/Pb37	Pb-Free
Average Ramp Rate (T_L to T_P)	1.25°C/sec maximum	1.25°C/sec maximum
Preheat		
Minimum Temperature (T_{SMIN})	100°C	150°C
Maximum Temperature (T_{SMAX})	150°C	200°C
Time (T_{SMIN} to T_{SMAX}), t_S	60 sec to 75 sec	60 sec to 75 sec
Ramp-Up Rate (T_{SMAX} to T_L)	1.25°C/sec	1.25°C/sec
Time Maintained Above Liquidous (t_L)	45 sec to 75 sec	~50 sec
Liquidous Temperature (T_L)	183°C	217°C
Peak Temperature (T_P)	215°C + 3°C/-3°C	260°C + 0°C/-5°C
Time Within 5°C of Actual Peak Temperature (t_P)	20 sec to 30 sec	20 sec to 30 sec
Ramp-Down Rate	3°C/sec maximum	3°C/sec maximum
Time 25°C to Peak Temperature	5 minutes maximum	5 minutes maximum

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



TOP VIEW
(TERMINAL SIDE DOWN)
Not to Scale

10140-003

Figure 4. Pin Configuration

Table 4. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	OUTPUT	Analog Output Signal
2	GND	Ground
3	V _{DD}	Power Supply

TYPICAL PERFORMANCE CHARACTERISTICS

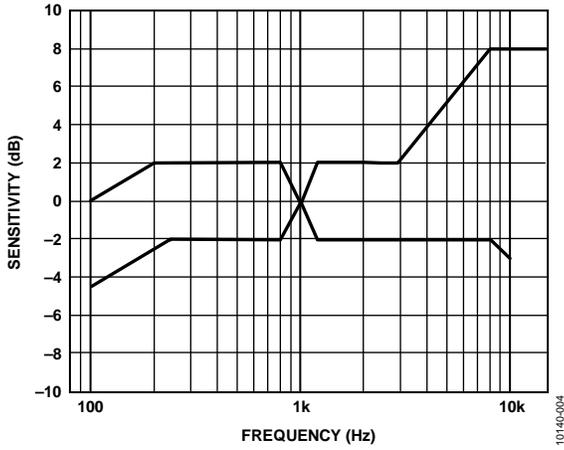


Figure 5. Frequency Response Mask

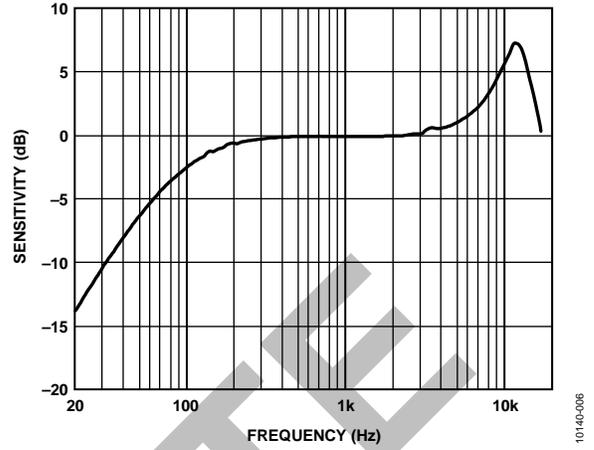


Figure 7. Typical Frequency Response (Measured)

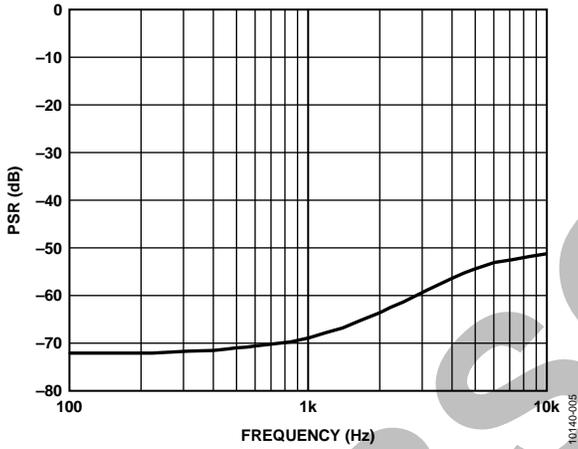


Figure 6. Typical Power Supply Rejection vs. Frequency

APPLICATIONS INFORMATION

The ADMP504 output can be connected to a dedicated codec microphone input (see Figure 8) or to a high input impedance gain stage (see Figure 9). A 0.1 μF ceramic capacitor placed close to the ADMP504 supply pin is used for testing and is recommended to adequately decouple the microphone from noise on the power supply. A dc-blocking capacitor is required at the output of the microphone. This capacitor creates a high-pass filter with a corner frequency at

$$f_c = 1/(2\pi \times C \times R)$$

where R is the codec's input impedance.

A minimum value of 2.2 μF is recommended in Figure 8 because the input impedance of the ADAU1361/ADAU1761 can be as low as 2 k Ω at its highest PGA gain setting, which would result in a high-pass filter corner frequency at about 37 Hz.

Figure 9 shows the ADMP504 connected to an ADA4897-1 op amp configured as a noninverting preamplifier.

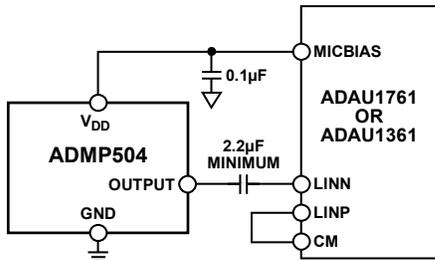


Figure 8. ADMP504 Connected to the Analog Devices ADAU1761 or ADAU1361 Codec

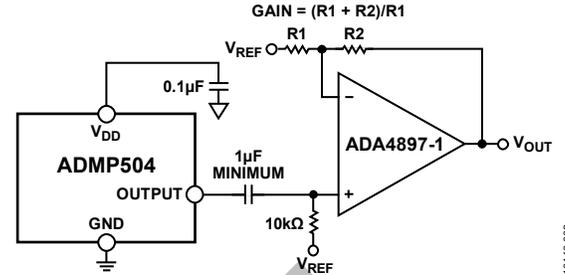


Figure 9. ADMP504 Connected to the ADA4897-1 Op Amp

SUPPORTING DOCUMENTS

Evaluation Board User Guide

UG-325, EVAL-ADMP504Z-FLEX: Bottom-Ported Analog Output MEMS Microphone Evaluation Board

Circuit Note

CN-0207, High Performance Analog MEMS Microphone's Simple Interface to SigmaDSP Audio Codec

Application Notes

AN-1003, Recommendations for Mounting and Connecting Analog Devices, Inc., Bottom-Ported MEMS Microphones

AN-1068, Reflow Soldering of the MEMS Microphone

AN-1112, Microphone Specifications Explained

AN-1124, Recommendations for Sealing Analog Devices, Inc., Bottom-Port MEMS Microphones from Dust and Liquid Ingress

AN-1140, Microphone Array Beamforming

HANDLING INSTRUCTIONS

PICK-AND-PLACE EQUIPMENT

The MEMS microphone can be handled using standard pick-and-place and chip shooting equipment. Take care to avoid damage to the MEMS microphone structure as follows:

- Use a standard pickup tool to handle the microphone. Because the microphone hole is on the bottom of the package, the pickup tool can make contact with any part of the lid surface.
- Use care during pick-and-place to ensure that no high shock events above 10 kg are experienced because this may cause damage to the microphone.
- Do not pick up the microphone with a vacuum tool that makes contact with the bottom side of the microphone. Do not pull air out or blow air into the microphone port.
- Do not use excessive force to place the microphone on the PCB.

REFLOW SOLDER

For best results, the soldering profile should be in accordance with the recommendations of the manufacturer of the solder paste used to attach the MEMS microphone to the PCB. It is recommended that the solder reflow profile not exceed the limit conditions specified in Figure 3 and Table 3.

BOARD WASH

When washing the PCB, ensure that water does not make contact with the microphone port. Blow-off procedures and ultrasonic cleaning must not be used.

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PCB LAND PATTERN LAYOUT

The recommended PCB land pattern for the ADMP504 should be laid out to a 1:1 ratio to the solder pads on the microphone package, as shown in Figure 10. Take care to avoid applying solder paste to the sound hole in the PCB. A suggested solder

paste stencil pattern layout is shown in Figure 11. The diameter of the sound hole in the PCB should be larger than the diameter of the sound port of the microphone. A minimum diameter of 0.5 mm is recommended.

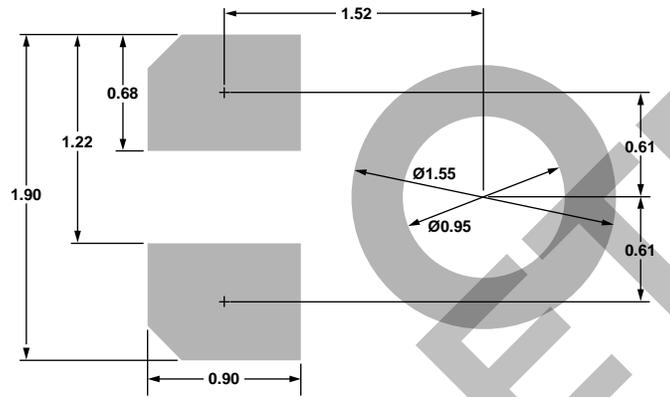


Figure 10. PCB Land Pattern Layout

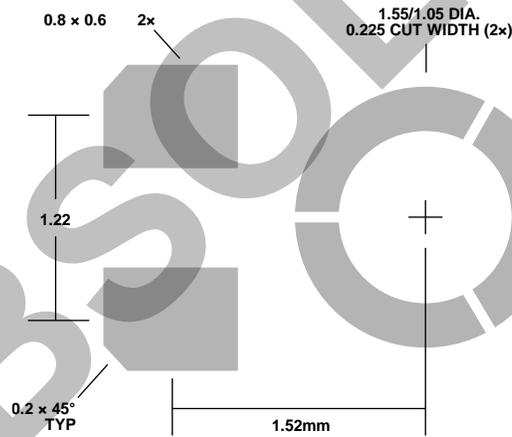


Figure 11. Suggested Solder Paste Stencil Pattern Layout

RELIABILITY SPECIFICATIONS

The microphone sensitivity after stress must deviate by no more than 3 dB from the initial value.

Table 5.

Stress Test	Description
Low Temperature Operating Life	−40°C, 1000 hrs, powered
High Temperature Operating Life	+125°C, 1000 hrs, powered
Temperature Humidity Bias (THB)	+85°C/+85% relative humidity (RH), 1000 hrs, powered
Temperature Cycle	−40°C/+125°C, one cycle per hour, 1000 cycles
High Temperature Storage	+150°C, 1000 hrs
Low Temperature Storage	−40°C, 1000 hrs
Component CDM ESD	All pins, 0.5 kV
Component HBM ESD	All pins, 1.5 kV
Component MM ESD	All pins, 0.2 kV

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OUTLINE DIMENSIONS

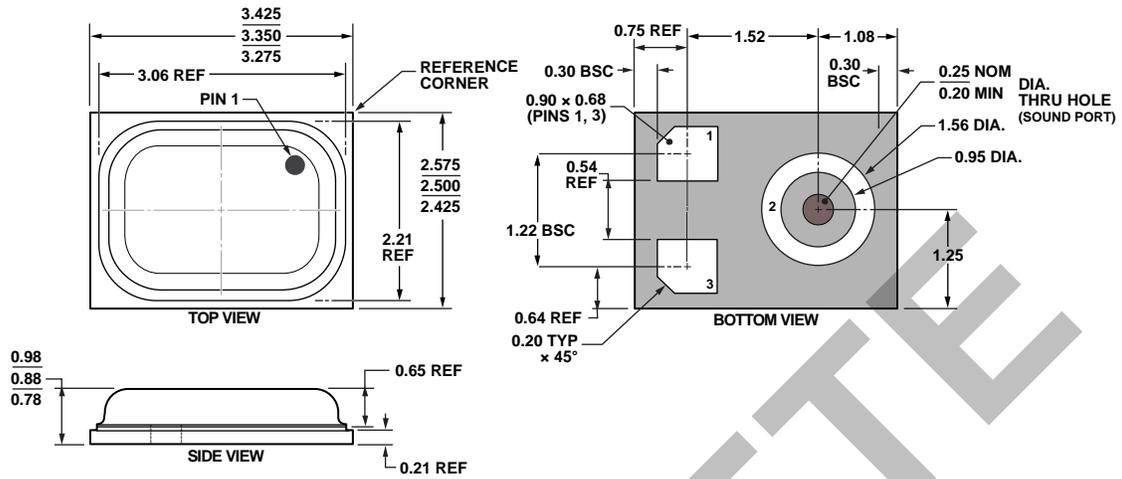


Figure 12. 3-Terminal Chip Array Small Outline No Lead Cavity [LGA_CAV]
 3.35 mm × 2.50 mm Body
 (CE-3-2)
 Dimensions shown in millimeters

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ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option ²	Ordering Quantity
ADMP504ACEZ-RL	-40°C to +85°C	3-Terminal LGA_CAV, 13" Tape and Reel	CE-3-2	10,000
ADMP504ACEZ-RL7	-40°C to +85°C	3-Terminal LGA_CAV, 7" Tape and Reel	CE-3-2	1,000
EVAL-ADMP504Z-FLEX		Flex Evaluation Board		

¹ Z = RoHS Compliant Part.

² This package option is halide free.

NOTES

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